

Notification Number:	20220705000.0	Notification Date:	July 22, 2022
Title:	Datasheet for CDx4HCT573, SNx4HC109, SN74HCT244-Q1, SN74HC244-Q1 and SN74HC573A-Q1		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



CD54HCT573, CD74HCT573

SCLS455E – FEBRUARY 2001 – REVISED JUNE 2022

Changes from Revision D (January 2022) to Revision E (June 2022) Page

- Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, DB was 70 is now 122.7, N was 69 is now 84.6.....4



SN54HC109, SN74HC109

SCLS470C – MARCH 2003 – REVISED JUNE 2022

Changes from Revision B (February 2022) to Revision C (June 2022) Page

- Junction-to-ambient thermal resistance values increased. D was 73 is now 117.2, N was 67 is now 60.5, NS was 64 is now 88.3.....4



SN74HCT244-Q1

SCLS509C – JUNE 2003 – REVISED JUNE 2022

Changes from Revision B (February 2022) to Revision C (June 2022) Page

- Junction-to-ambient thermal resistance values increased. PW was 83 is now 131.8.....4



SN74HC244-Q1

SCLS543C – SEPTEMBER 2002 – REVISED JUNE 2022

Changes from Revision B (February 2022) to Revision C (June 2022) Page

- Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, PW was 83 is now 131.8.....4



SN74HC573A-Q1

SCLS600C – NOVEMBER 2004 – REVISED JUNE 2022

Changes from Revision B (February 2022) to Revision C (June 2022) Page

- Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, PW was 83 is now 131.8.....4

The datasheet number will be changing.

Device Family	Change From:	Change To:
CDx4HCT573	SCLS455D	SCLS455E
SNx4HC109	SCLS470B	SCLS470C
SN74HCT244-Q1	SCLS509B	SCLS509C
SN74HC244-Q1	SCLS543B	SCLS543C
SN74HC573A-Q1	SCLS600B	SCLS600C

These changes may be reviewed at the datasheet links provided.

<https://www.ti.com/product/CD54HCT573>

<https://www.ti.com/product/SN54HC109>

<https://www.ti.com/product/SN74HCT244-Q1>

<https://www.ti.com/product/SN74HC244-Q1>

<https://www.ti.com/product/SN74HC573A-Q1>

Error! Bookmark not defined.

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:

None.

Product Affected:

CD74HCT573DBR	CD74HCT573M96G4	SN74HC109NE4	SN74HC244QPWRQ1
CD74HCT573E	SN74HC109D	SN74HC109NSR	SN74HC573AQDWRQ1
CD74HCT573EE4	SN74HC109DR	SN74HC109NSRE4	SN74HC573AQPWRG4Q1
CD74HCT573M	SN74HC109DRG4	SN74HC244QDWRQ1	SN74HCT244QPWRG4Q1
CD74HCT573M96	SN74HC109N	SN74HC244QPWRG4Q1	SN74HCT244QPWRQ1

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Location	E-Mail
WW PCN Team	PCN_ww_admin_team@list.ti.com

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